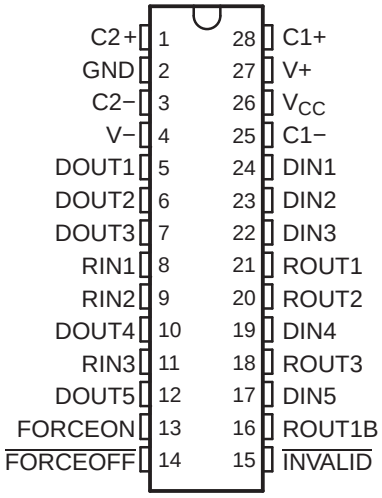
FEATURES

- **Auto-Powerdown Plus**
- **Operates With 3-V to 5.5-V V_{CC} Supply**
- **Always-Active Noninverting Receiver Output (ROUT1B)**
- **Supports Operation From 250 kbit/s to 1 Mbit/s**
- **Low Standby Current . . . 1 µA Typical**
- **External Capacitors . . . 4 × 0.1 µF**
- **Accepts 5-V Logic Input With 3.3-V Supply**
- **Inter-Operable With TRSF3243**
- **RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)**

DB, DW, OR PW PACKAGE
(TOP VIEW)



APPLICATIONS

- **Battery-Powered Systems**
- **PDAs**
- **Notebooks**
- **Subnotebooks**
- **Laptops**
- **Palmtop PCs**
- **Hand-Held Equipment**
- **Modems**
- **Printers**

DESCRIPTION/ORDERING INFORMATION

The TRSF3238 device consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port connection pins, including GND). The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, this device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. This device operates at data signaling rate up to 1 Mbit/s and at an increased slew-rate range of 24 V/µs to 150 V/µs.

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 µA. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high. With auto-powerdown plus enabled, the device automatically activates when a valid signal is applied to any receiver or driver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V, or has been between –0.3 V and 0.3 V for less than 30 µs. $\overline{\text{INVALID}}$ is low (invalid data) if all receiver input voltages are between –0.3 V and 0.3 V for more than 30 µs. Refer to Figure 5 for receiver input levels.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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ORDERING INFORMATION

T_A	PACKAGE(1)(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC – DW	Tube of 50	TRSF3238CDW	TRS3238EC
		Reel of 2000	TRSF3238CDWR	
	SSOP – DB	Tube of 50	TRSF3238CDB	TRS3238EC
		Reel of 2000	TRSF3238CDBR	
	TSSOP – PW	Tube of 50	TRSF3238CPW	RT38C
		Reel of 2000	TRSF3238CPWR	
–40°C to 85°C	SOIC – DW	Tube of 50	TRSF3238IDW	TRS3238EI
		Reel of 2000	TRSF3238IDWR	
	SSOP – DB	Tube of 50	TRSF3238IDB	TRS3238EI
		Reel of 2000	TRSF3238IDBR	
	TSSOP – PW	Tube of 50	TRSF3238IPW	RT38I
		Reel of 2000	TRSF3238IPWR	

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTION TABLES

Each Driver(1)

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	$\overline{\text{FORCEOFF}}$	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown plus disabled
H	H	H	X	L	
L	L	H	<30 s	H	Normal operation with auto-powerdown plus enabled
H	L	H	<30 s	L	
L	L	H	>30 s	Z	Powered off by auto-powerdown plus feature
H	L	H	>30 s	Z	

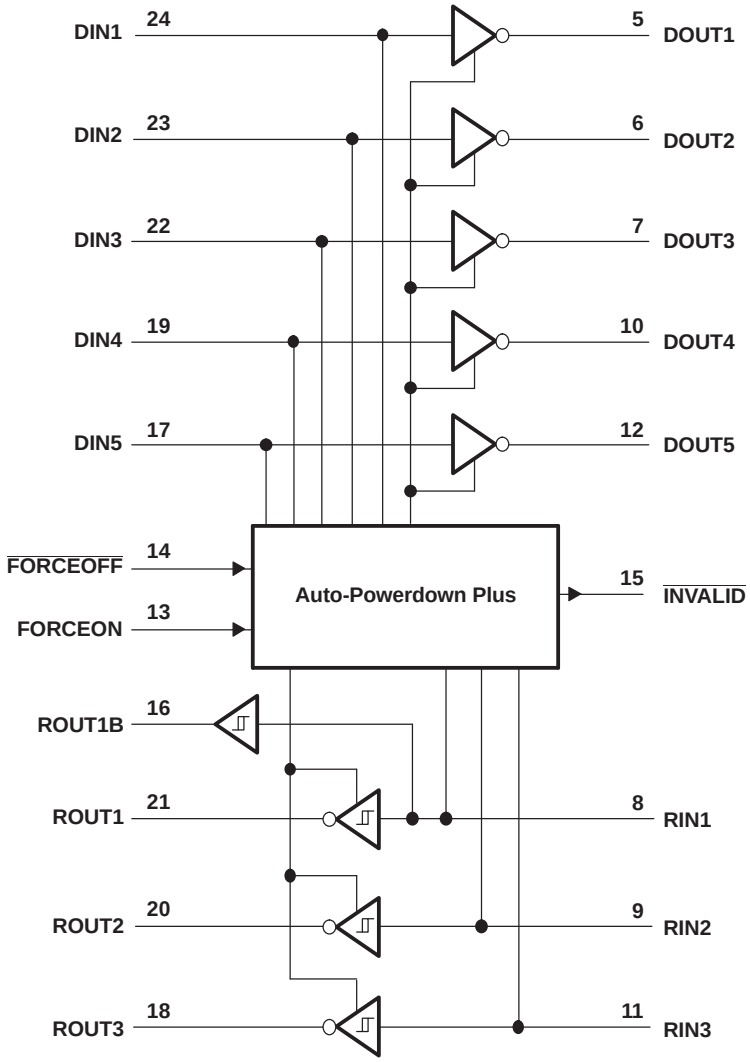
(1) H = high level, L = low level, X = irrelevant, Z = high impedance

Each Receiver(1)

INPUTS				OUTPUTS		RECEIVER STATUS
RIN2	RIN1, RIN3–RIN5	$\overline{\text{FORCEOFF}}$	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	
L	X	L	X	L	Z	Powered off while ROUT1B is active
H	X	L	X	H	Z	
L	L	H	<30 s	L	H	Normal operation with auto-powerdown plus disabled/enabled
L	H	H	<30 s	L	L	
H	L	H	<30 s	H	H	
H	H	H	<30 s	H	L	
Open	Open	H	>30 s	L	H	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range(2)		–0.3	6	V
V+	Positive-output supply voltage range(2)		–0.3	7	V
V–	Negative-output supply voltage range(2)		0.3	–7	V
V+ – V–	Supply voltage difference(2)			13	V
V_I	Input voltage range	Driver ($\overline{\text{FORCEOFF}}$, FORCEON)	–0.3	6	V
		Receiver	–25	25	
V_O	Output voltage range	Driver	–13.2	13.2	V
		Receiver ($\overline{\text{INVALID}}$)	–0.3	V_{CC} + 0.3	
θ_{JA}	Package thermal impedance(3)(4)	DB package		62	°C/W
		DW package		46	
		PW package		62	
T_J	Operating virtual junction temperature			150	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network GND.
(3) Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions(1)

See Figure 6

				MIN	NOM	MAX	UNIT
	Supply voltage		V_{CC} = 3.3 V	3	3.3	3.6	V
			V_{CC} = 5 V	4.5	5	5.5	
V_{IH}	Driver and control high-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON	V_{CC} = 3.3 V	2			V
			V_{CC} = 5 V	2.4			
V_{IL}	Driver and control low-level input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON				0.8	V
V_I	Driver and control input voltage	DIN, $\overline{\text{FORCEOFF}}$, FORCEON		0		5.5	V
V_I	Receiver input voltage			–25		25	V
T_A	Operating free-air temperature		TRSF3238C	0		70	°C
			TRSF3238I	–40		85	

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER			TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
I_I	Input leakage current	$\overline{\text{FORCEOFF}}$, FORCEON			±0.01	±1	µA
I_{CC}	Supply current	Auto-powerdown plus disabled	No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V_{CC}		0.5	2	mA
		Powered off	No load, $\overline{\text{FORCEOFF}}$ at GND		1	10	µA
		Auto-powerdown plus enabled	No load, $\overline{\text{FORCEOFF}}$ at V_{CC}, FORCEON at GND, All RIN are open or grounded		1	10	

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

DRIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER		TEST CONDITIONS			MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	All DOUT at R_L = 3 kΩ to GND			5	5.4		V
V_{OL}	Low-level output voltage	All DOUT at R_L = 3 kΩ to GND			–5	–5.4		V
I_{IH}	High-level input current	$V_I = V_{CC}$				±0.01	±1	µA
I_{IL}	Low-level input current	V_I at GND				±0.01	±1	µA
I_{OS}	Short-circuit output current(3)	V_{CC} = 3.6 V,	V_O = 0 V			±35	±60	mA
		V_{CC} = 5.5 V,	V_O = 0 V			±40	±90	
r_o	Output resistance	V_{CC}, V+, and V– = 0 V,	V_O = ±2 V		300	10M		Ω
I_{off}	Output leakage current	$\overline{\text{FORCEOFF}}$ = GND	V_O = ±12 V,	V_{CC} = 3 V to 3.6 V			±25	µA
			V_O = ±10 V,	V_{CC} = 4.5 V to 5.5 V			±25	

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Switching Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER		TEST CONDITIONS			MIN	TYP(2)	MAX	UNIT
	Maximum data rate (see Figure 1)	R_L = 3 kΩ, One DOUT switching	C_L = 1000 pF		250			kbit/s
			C_L = 250 pF,	V_{CC} = 3 V to 4.5 V	1000			
			C_L = 1000 pF,	V_{CC} = 4.5 V to 5.5 V	1000			
$t_{sk(p)}$	Pulse skew(3)	C_L = 150 pF to 2500 pF,	R_L = 3 kΩ to 7 kΩ,	See Figure 2		25		ns
SR(tr)	Slew rate, transition region (see Figure 1)	C_L = 150 pF to 1000 pF,	R_L = 3 kΩ to 7 kΩ,	V_{CC} = 3.3 V	18		150	V/µs

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

RECEIVER SECTION

Electrical Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = –1 mA	V_{CC} – 0.6	V_{CC} – 0.1		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6 mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 3.3 V		1.5	2.4	V
		V_{CC} = 5 V		1.8	2.4	
$V_{IT–}$	Negative-going input threshold voltage	V_{CC} = 3.3 V	0.6	1.2		V
		V_{CC} = 5 V	0.8	1.5		
V_{hys}	Input hysteresis ($V_{IT+} – V_{IT–}$)			0.3		V
I_{off}	Output leakage current (except ROUT1B)	$\overline{FORCEOFF}$ = 0 V		±0.05	±10	µA
r_i	Input resistance	V_I = ±3 V to ±25 V	3	5	7	kΩ

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

Switching Characteristics(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP(2)	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 150 pF, See Figure 3	150	ns
t_{PHL}	Propagation delay time, high- to low-level output	C_L = 150 pF, See Figure 3	150	ns
t_{en}	Output enable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
t_{dis}	Output disable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
$t_{sk(p)}$	Pulse skew(3)	See Figure 3	50	ns

(1) Testing supply conditions are C1–C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.
(2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} – t_{PHL}|$ of each channel of the same device.

AUTO-POWERDOWN PLUS SECTION

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}		2.7	V
$V_{T-(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	–2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{INVALID}$ low-level output voltage	FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	–0.3	0.3	V
V_{OH}	$\overline{INVALID}$ high-level output voltage	I_{OH} = –1 mA, FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}	V_{CC} – 0.6		V
V_{OL}	$\overline{INVALID}$ low-level output voltage	I_{OL} = 1.6 mA, FORCEON = GND, $\overline{FORCEOFF}$ = V_{CC}		0.4	V

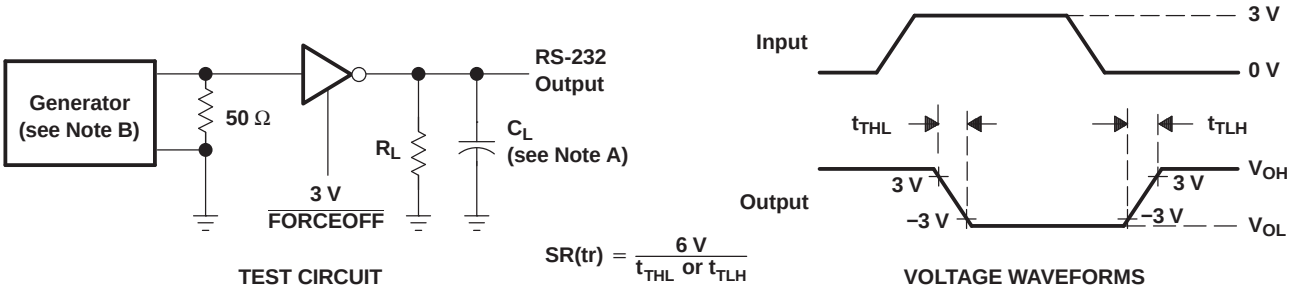
Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER		MIN	TYP(1)	MAX	UNIT
t_{valid}	Propagation delay time, low- to high-level output		0.1		µs
$t_{invalid}$	Propagation delay time, high- to low-level output		50		µs
t_{en}	Supply enable time		25		µs
t_{dis}	Receiver or driver edge to auto-powerdown plus	15	30	60	s

(1) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

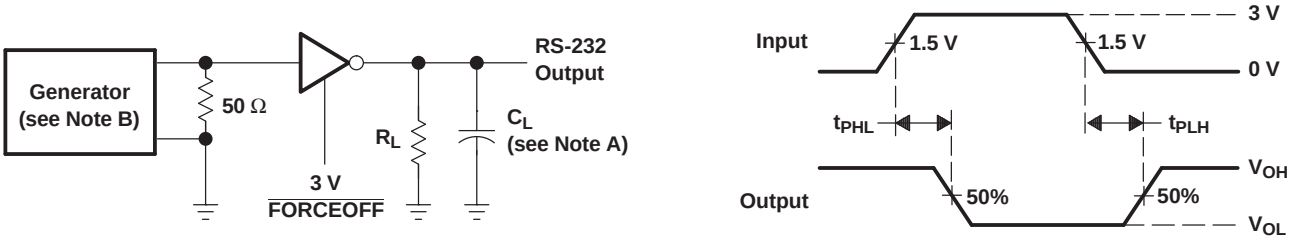


TEST CIRCUIT VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 1. Driver Slew Rate

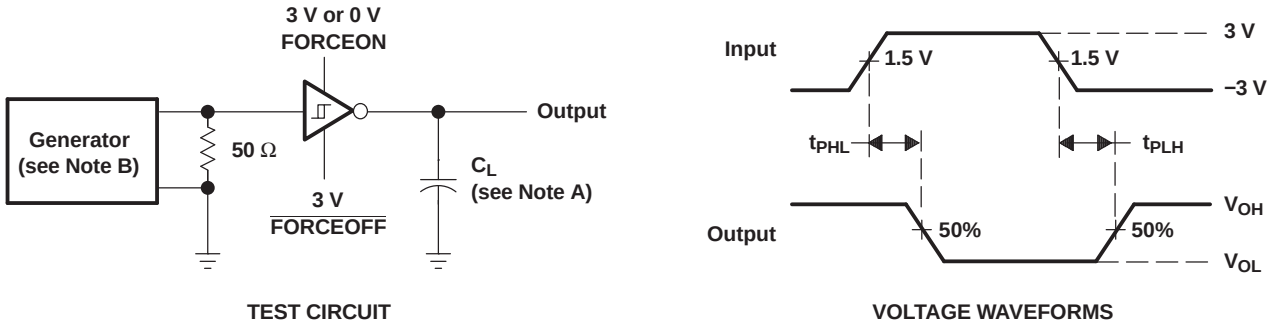


TEST CIRCUIT VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 1 Mbit/s, Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 2. Driver Pulse Skew



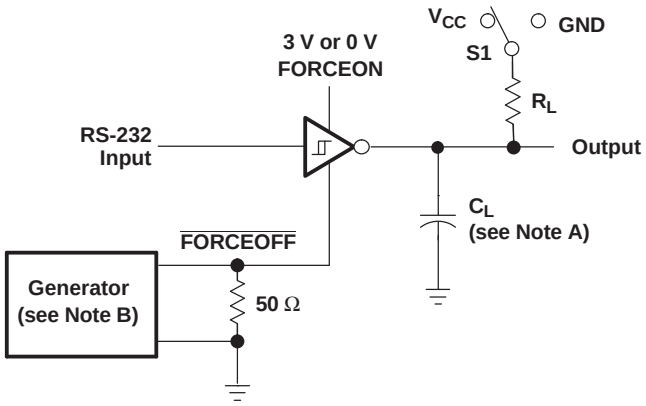
TEST CIRCUIT VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

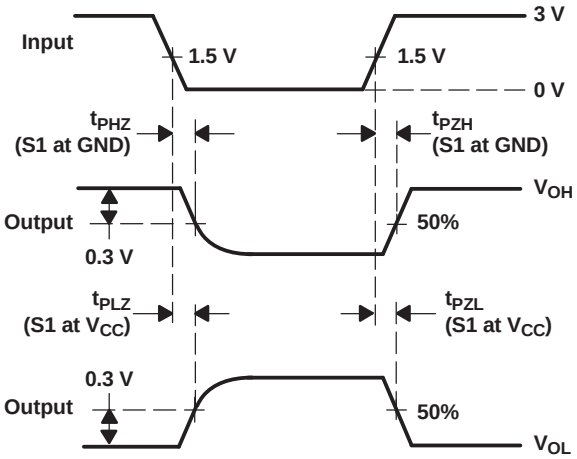
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT



VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

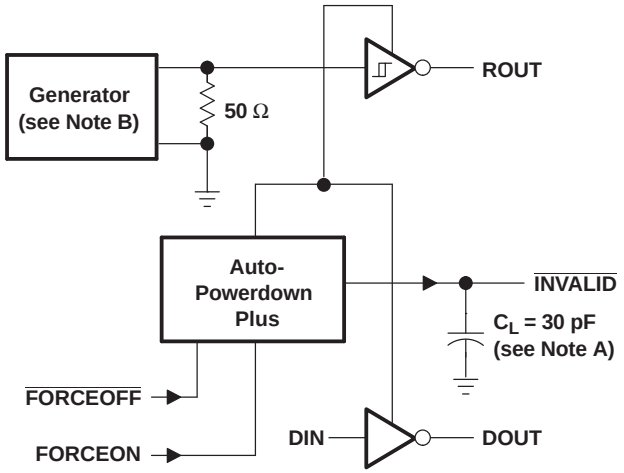
B. The pulse generator has the following characteristics: Z_O = 50 Ω, 50% duty cycle, t_r ≤ 10 ns, t_f ≤ 10 ns.

C. t_{PLZ} and t_{PHZ} are the same as t_{dis}.

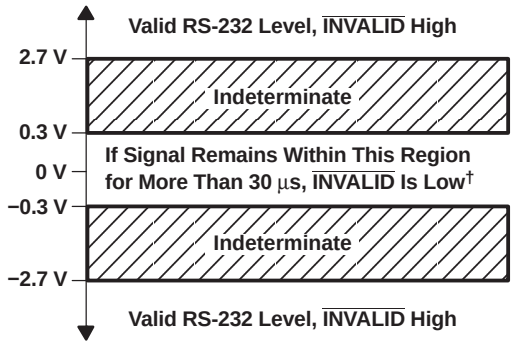
D. t_{PZL} and t_{PZH} are the same as t_{en}.

Figure 4. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION (continued)

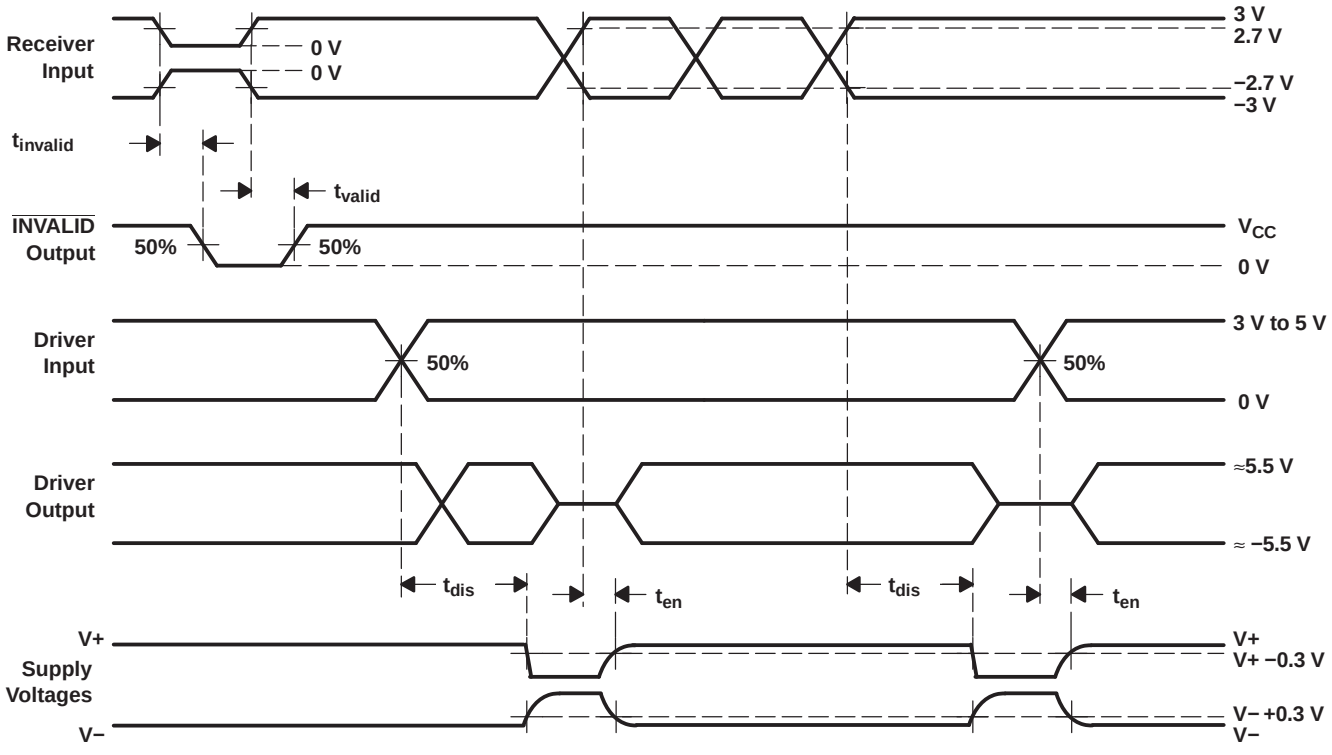


TEST CIRCUIT



† Auto-powerdown plus disables drivers and reduces supply current to 1 μA.

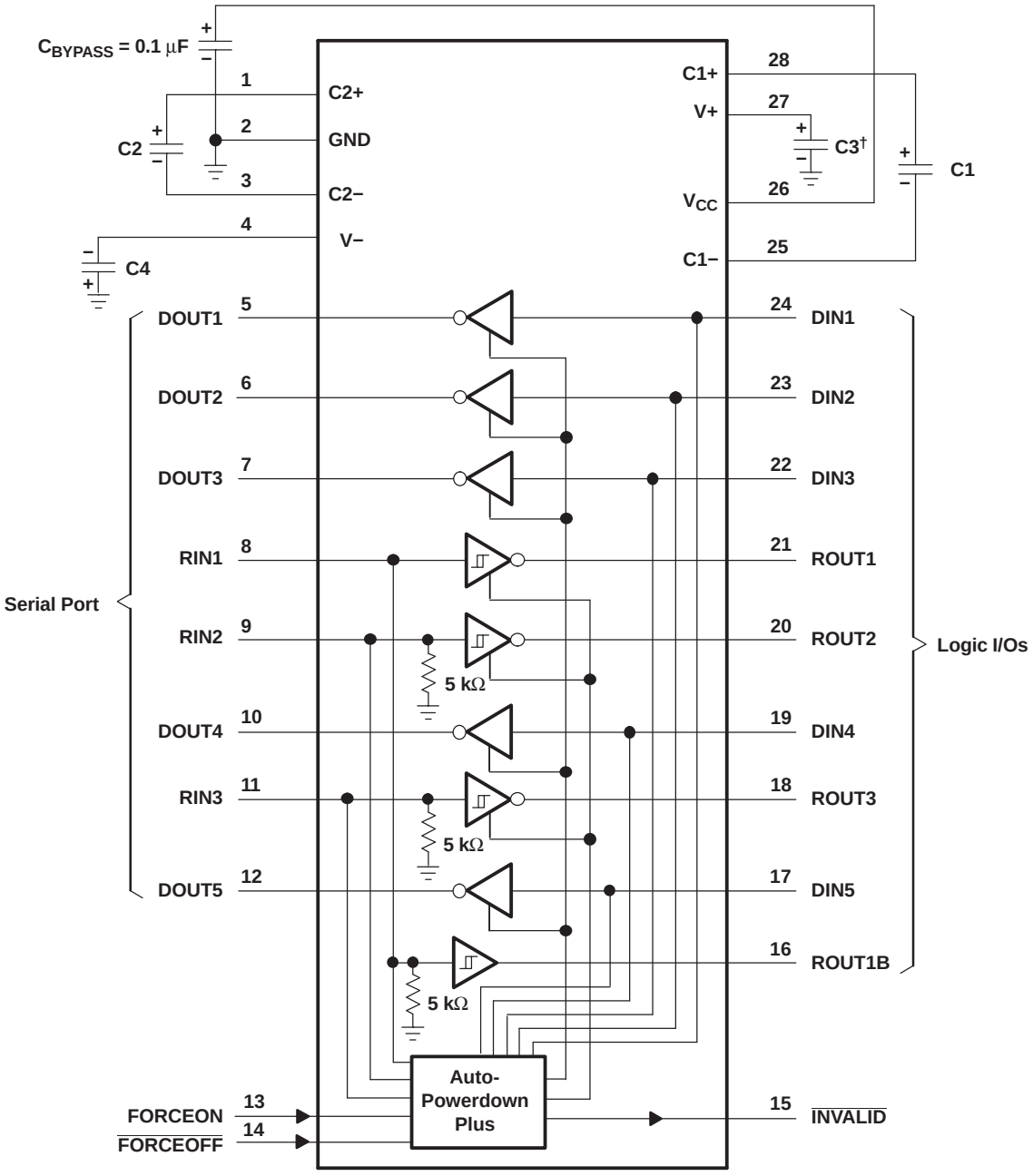
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, Z_O = 50 Ω, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.



Voltage Waveforms and Timing Diagrams

Figure 5. INVALID Propagation-Delay Times and Supply-Enabling Time

APPLICATION INFORMATION



V_{CC} vs CAPACITOR VALUES

V_{CC}	C1	C2, C3, and C4
3.3 V ± 0.15 V	0.1 µF	0.1 µF
3.3 V ± 0.3 V	0.22 µF	0.22 µF
5 V ± 0.5 V	0.047 µF	0.33 µF
3 V to 5.5 V	0.22 µF	1 µF

† C3 can be connected to V_{CC} or GND.
A.Resistor values shown are nominal.

Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TRSF3238CDB	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDBG4	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDBR	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDBRG4	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDW	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDWG4	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDWR	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CDWRG4	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CPW	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CPWG4	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CPWR	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238CPWRG4	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDB	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDBG4	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDBR	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDBRG4	ACTIVE	SSOP	DB	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDW	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDWG4	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDWR	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IDWRG4	ACTIVE	SOIC	DW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IPW	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IPWG4	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IPWR	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples
TRSF3238IPWRG4	ACTIVE	TSSOP	PW	28		TBD	Call TI	Call TI	Purchase Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

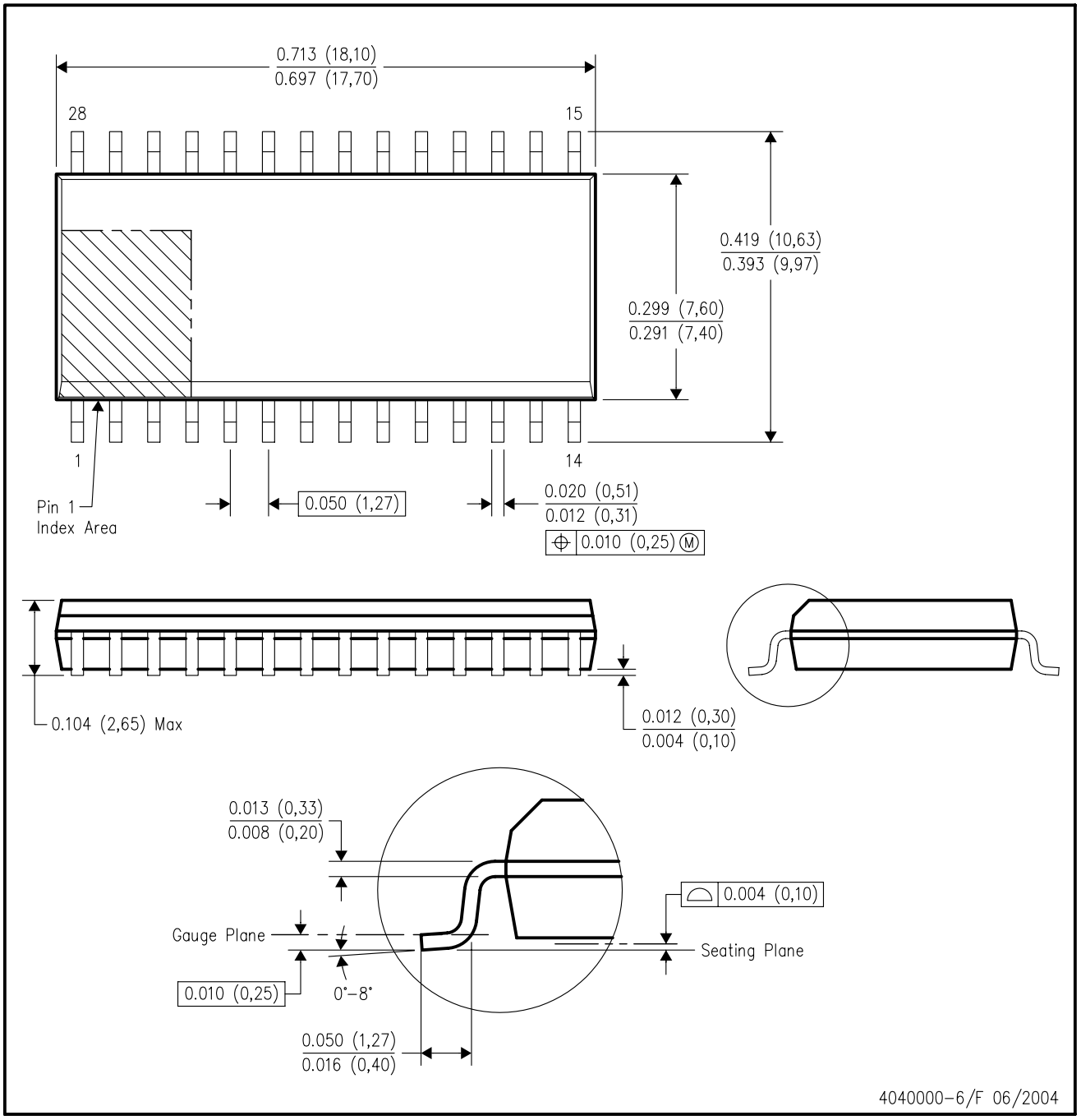
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DW (R–PDSO–G28) PLASTIC SMALL–OUTLINE PACKAGE

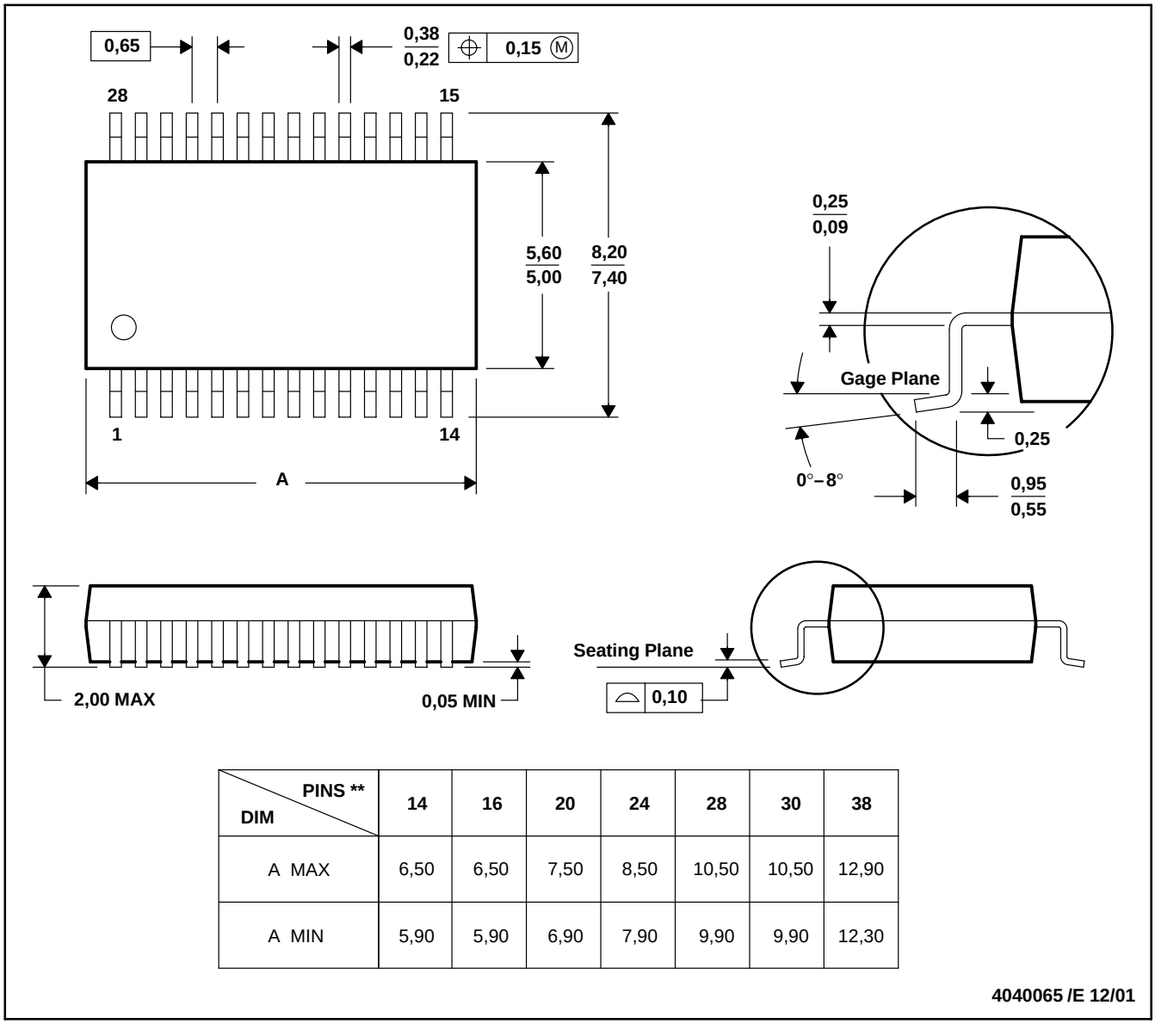


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AE.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



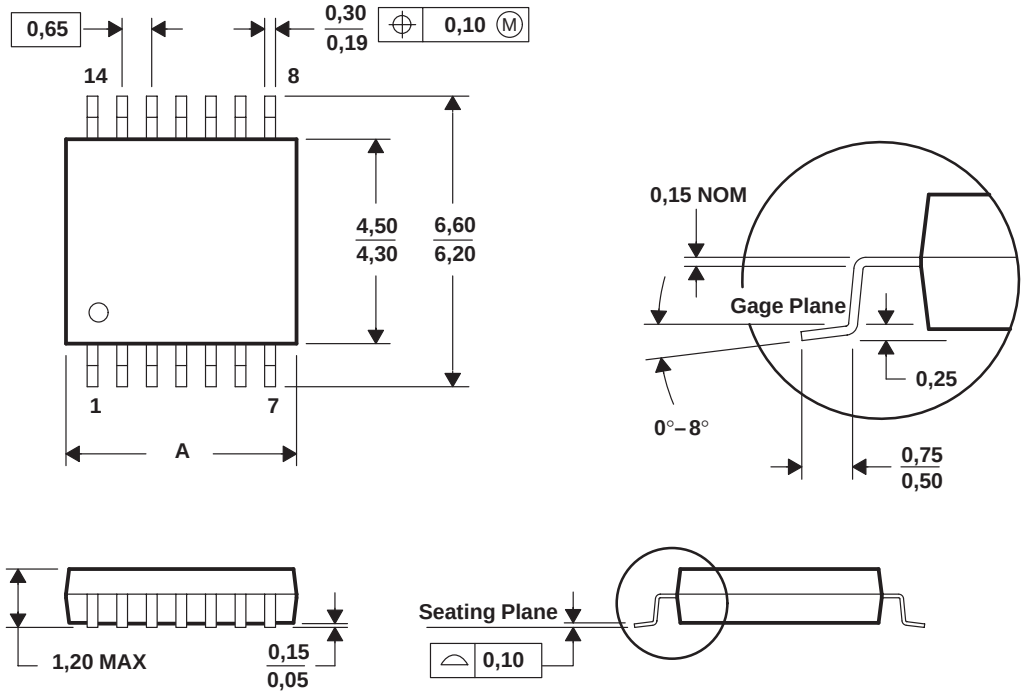
DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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